Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("6017272").PN.	USPAT; USOCR	OR	OFF	2006/01/09 15:51
L2	0	("601727259478236203431").PN.	USPAT; USOCR	OR	OFF	2006/01/09 15:53
L3	0	("6017272,5947823,6203431").PN.	USPAT; USOCR	OR	OFF	2006/01/09 15:52
L4	54	"6017272", "5947823", "6203431"	USPAT	OR	OFF	2006/01/09 15:52
L5	3	(("6017272") or ("5947823") or ("6203431")).PN.	USPAT; USOCR	OR	OFF	2006/01/09 16:35
L6	1	("5867368").PN.	USPAT; USOCR	OR	OFF	2006/01/09 16:35
S1	55145	(chip and (pad or pads) and (wire or wiring))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 12:55
S2	481	(chip and (pad or pads) and (wire or wiring) and (liquid adj resin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 09:02
S3	12508	ic adj package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 14:26
S5	2629	S3 and (spacer or ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 14:27
S6	305	S5 and elastic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:13
S7	24420	ball adj grid adj array or bga	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 14:29

S8	191	S3 and S6 and S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 14:29
S10	16	TOMIMATSU-HIROYUKI	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:43
S13	3	"2001060657"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:44
S14	2	"08088316"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:45
S15	2	"2001308262"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:46
S17	1	"2001514449"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:47
S18	3	"2000058743"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:48
S19	2	"2002222913"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:49

S20	3	"08288455"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:50
S21	5	"2004006670"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:51
S22	7	"9910925"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/29 15:51
S23	481	(chip and (pad or pads) and (wire or wiring) and (liquid adj resin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 13:30
S24	265	S23 and (spacer or ball)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 10:56
S29	308	(chip and (pad or pads) and (wire or wiring) and (liquid adj resin) and (bump or bumps))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 10:10
S30	2	"20030057539"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 10:10
S31	482	(chip and (pad or pads) and (wire or wiring) and (liquid adj resin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 10:57

S32	88	S31 and (spacer or ball) and parallel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 10:57
S33	99	(chip and (pad or pads) and (wire or wiring) and (liquid adj resin) and (bump or bumps) and (parallel))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 13:31
S35	2537	257/777	USPAT	OR	OFF	2005/08/31 12:49
S36	0	("2002012556").PN.	USPAT; USOCR	OR	OFF	2005/08/31 16:56
S37	0	("20020125556").PN.	USPAT; USOCR	OR	OFF	2005/08/31 16:56
S38	0	10/015374	USPAT	OR	OFF	2005/08/31 16:56
S39	1	10/015374	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/31 16:57
S40	1	S39 and (curing or cured or cure or drying or dry or dried or hard$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/31 16:59
S41	4775	(adhensive or (liquid adj resin)) and (hardened or hardening or harden)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/20 17:10
S42	4174	S41 and @py<="2003"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/20 17:11
S43	30	S42 and chip and insulator	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/20 17:17

S44	340	S42 and chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 15:51
S45	2	"2002104570"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 12:56
S46	2	"20030189259"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 12:56
S47	4786	(adhensive or (liquid adj resin)) and (hardened or hardening or harden)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 13:08
S48	4174	S47 and @py<="2003"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/09 13:08